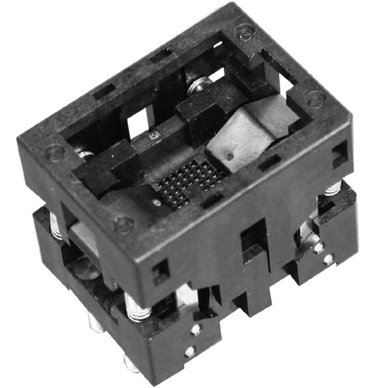
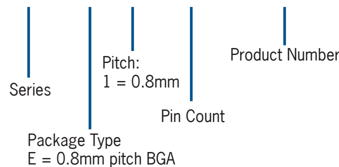
775E SERIES COMPACT CSP/FBGA

- 0.8mm Pitch
- Compression surface mount
- Z-axis compliant "U" shaped contact supports a wide variety of solder ball shape and composition
- Compact outline and low actuation force achieved through use of innovative latching mechanism
- Field exchangeable IC guide

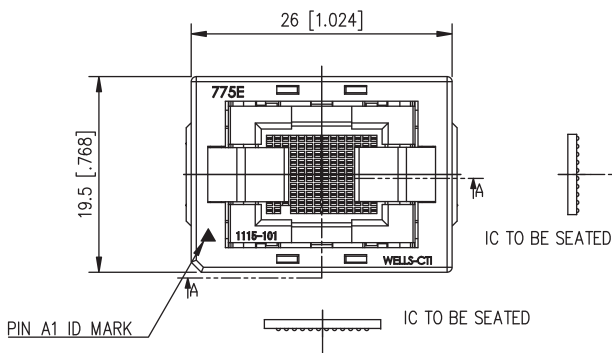


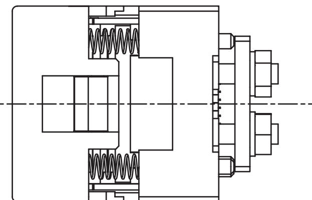
DESCRIPTION & ORDERING INFORMATION

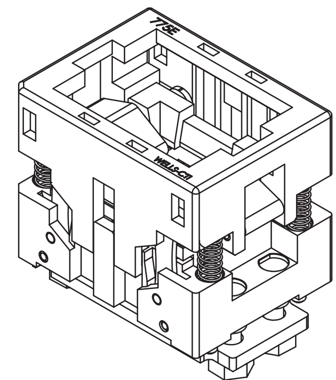


MATERIALS & SPECIFICATIONS

- Body Materials: PES, PEI, LCP or Equivalent
- Contact Material: Beryllium Copper Alloy
- Contact Plating: Gold
- Contact Force: 13 gram average
- Contact Resistance: 200~300 mΩ
- Temperature Rating: 150°C
- Durability: 10,000 cycles min.







Pitch e (mm)	Pin Count	Package Size (mm)	Pin Matrix.	Ball Dia. (mm)	Ball Height (mm)	Part Number
0.8	60	8X11.6	8X10	0.40	0.22	775E1060-101
	84	9X12	10X12	0.40	0.15	775E1084-101
	115	9X12	10X14	0.40	0.15	775E1115-101
	115	11X13	10X14	0.40	0.22	775E1115-102
	137	11X13	10X14	0.40	0.15	775E1137-101
	138	10X10	12X12	0.40	0.22	775E1138-101

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